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(54) Title: PERFLUORINATED HYDROCARBON POLYMER-FILLED ADHESIVE FORMULATIONS AND USES THEREFOR ☒			
(57) Abstract In accordance with the present invention, it has been discovered that perfluorinated hydrocarbon polymers can be used as fillers for the preparation of adhesive formulations having excellent dielectric properties, i.e., very low conductivities. Invention compositions display excellent rheological properties, in addition to low dielectric constants. Invention formulations can be used for a variety of purposes, such as, for example, for the preparations of filled adhesive formulations with a reduced propensity to settle out, excellent dispensing characteristics due to the dioxotropic nature thereof, and the like.			